

Abstract of the Disclosure

A method for manufacturing electronic devices using multiple layers of pre-porous dielectric materials that are made porous subsequent to etching and metal filling of apertures is provided. The pre-porous layers may be made porous sequentially or during a single processing step. Such pre-porous dielectric layers are selected not only to provide low dielectric constants after being made porous, but also to provide a difference in etch rates. Structures having such multiple layers of pre-porous dielectric layers are also provided.